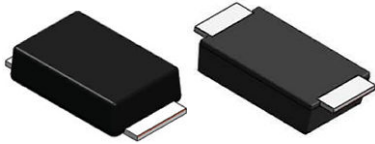


Hyperfast Rectifier, 2 A FRED Pt®

eSMP® Series



Top View

Bottom View

SlimSMAW (DO-221AD)

FEATURES

- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

DESIGN SUPPORT TOOLS

[click logo to get started](#)

3D
Models
Available

DESCRIPTION / APPLICATIONS

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial, and automotive applications.

MECHANICAL DATA

Case: SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating
Halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

Polarity: color band denotes the cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 A
V_R	100 V, 200 V
V_F at I_F	0.69 V
I_{FSM}	60 A
t_{rr} (typ.)	15 ns
T_J max.	175 °C
Package	SlimSMAW (DO-221AD)
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	VS-2EYH01-M3	V_{RRM}	100	V
	VS-2EYH02-M3		200	
Average rectified forward current	$I_{F(AV)}$ ⁽¹⁾	$T_C = 151\text{ °C}$	2	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25\text{ °C}$, 10 ms sine pulse wave	60	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

Note

⁽¹⁾ Mounted on infinite heatsink

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	VS-2EYH01-M3	V_{BR}, V_R	$I_R = 100\ \mu\text{A}$	100	-	-	V
	VS-2EYH02-M3			200	-	-	
Forward voltage, per diode	V_F	$I_F = 2\text{ A}$	-	0.86	0.93		
		$I_F = 2\text{ A}, T_J = 150\text{ °C}$	-	0.69	0.75		
Reverse leakage current, per diode	I_R	$V_R = V_R$ rated	-	-	2	μA	
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	20		
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	12	-	pF	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 1.0 A, di _F /dt = 50 A/μs, V _R = 30 V	-	22	-	ns
		I _F = 1.0 A, di _F /dt = 100 A/μs, V _R = 30 V	-	15	-	
		I _F = 0.5 A, I _R = 1A, I _{rr} = 0.25 A	-	-	28	
		T _J = 25 °C	-	16	-	
		T _J = 125 °C	-	26	-	
Peak recovery current	I _{RRM}	T _J = 25 °C	-	2.7	-	A
		T _J = 125 °C	-	3.4	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	-	20	-	nC
		T _J = 125 °C	-	43	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to mount	R _{thJM} ⁽¹⁾	Infinite heatsink	-	12	15	°C/W
Thermal resistance, junction to ambient	R _{thJA}	Device mounted on FR4 PCB, 2 oz. standard footprint	-	120	150	
Marking device	VS-2EYH01-M3	Case style SlimSMAW (DO-221AD)	2H1			
	VS-2EYH02-M3		2H2			

Note

(1) Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

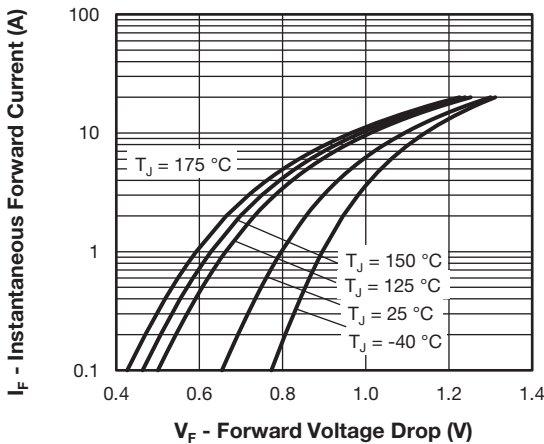


Fig. 1 - Typical Forward Voltage Drop Characteristics

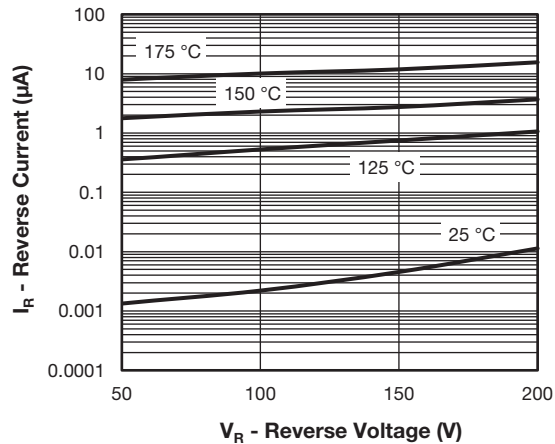


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

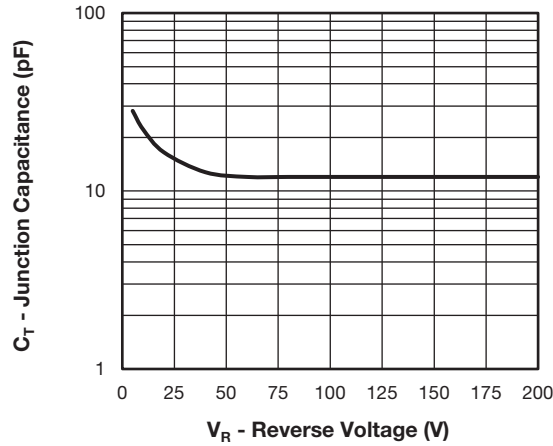


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

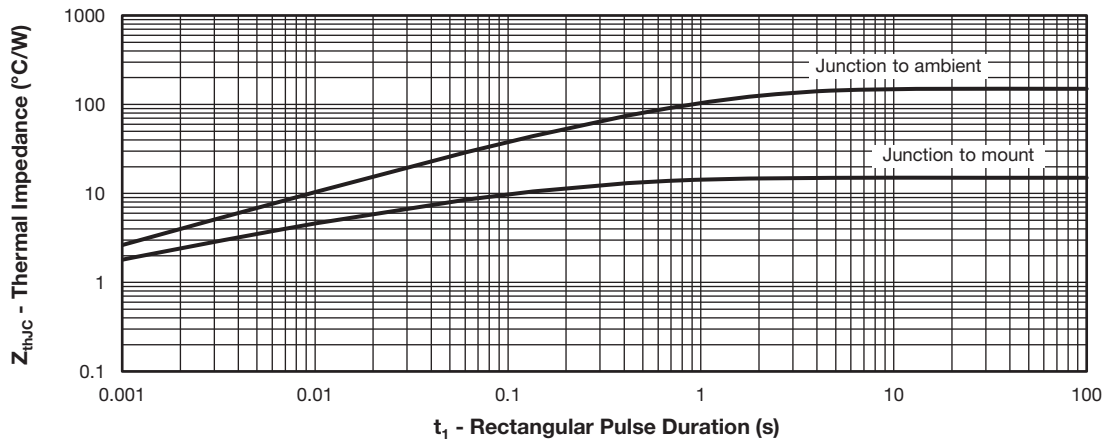


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

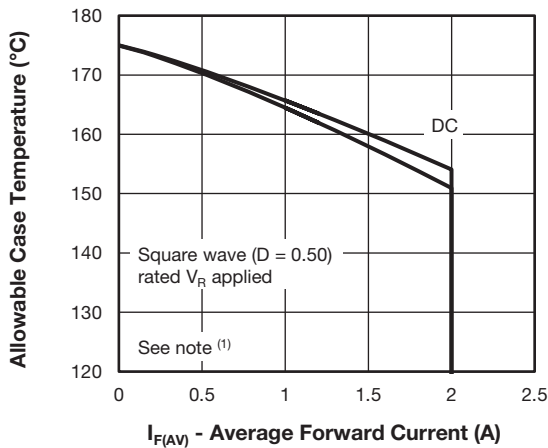


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

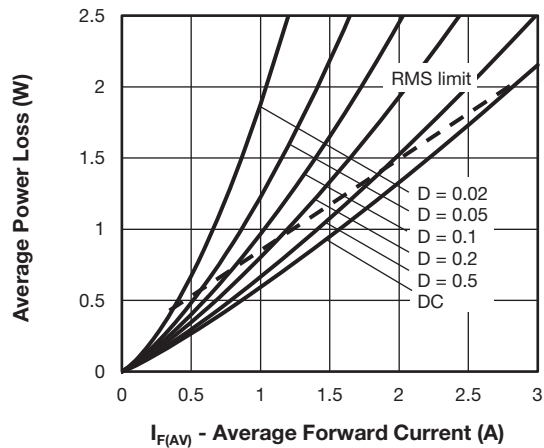


Fig. 6 - Forward Power Loss Characteristics

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
- P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

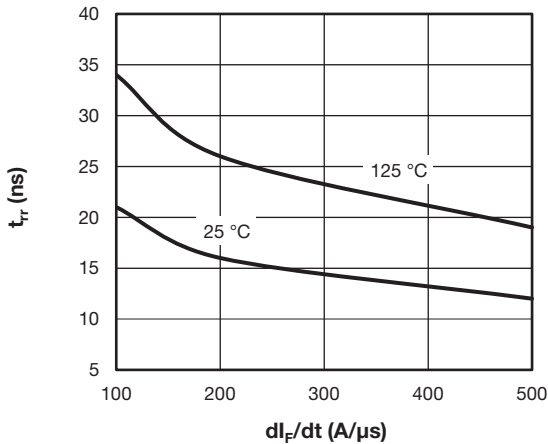


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt

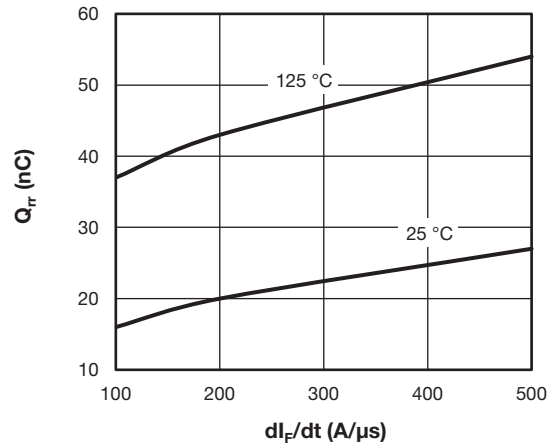


Fig. 8 - Typical Stored Charge vs. di_F/dt

ORDERING INFORMATION TABLE

Device code	VS-	2	E	Y	H	02	-	M3
	①	②	③	④	⑤	⑥		⑦
	1	2	3	4	5	6		7
	-	-	-	-	-	-		-
	Vishay Semiconductors product							
	Current rating (2 = 2 A)							
	Circuit configuration:							
	E = single diode							
	Y = SlimSMAW (DO-221AD)							
	Process type,							
	H = hyperfast recovery							
	Voltage code (02 = 200 V)							
	M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free							

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	PACKAGING DESCRIPTION
VS-2EYH01-M3/H	0.033	H	3500	7" diameter plastic tape and reel
VS-2EYH01-M3/I	0.033	I	14 000	13" diameter plastic tape and reel
VS-2EYH02-M3/H	0.033	H	3500	7" diameter plastic tape and reel
VS-2EYH02-M3/I	0.033	I	14 000	13" diameter plastic tape and reel

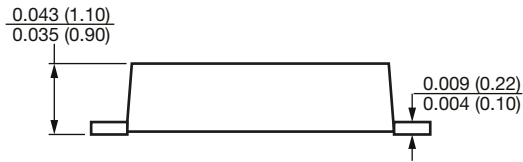
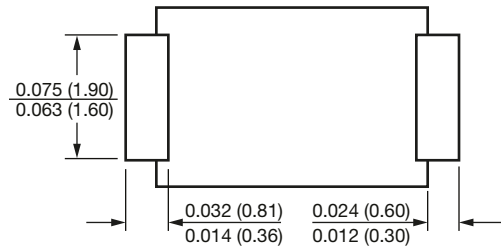
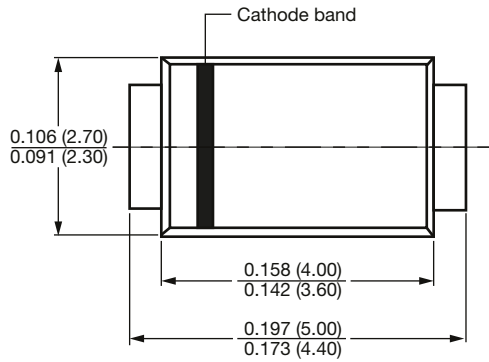
LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96582
Part marking information	www.vishay.com/doc?95562
Packaging information	www.vishay.com/doc?88869
SPIICE model	www.vishay.com/doc?96585



SlimSMAW (DO-221AD)

DIMENSIONS in inches (millimeters)

SlimSMAW (DO-221AD)



Mounting pad layout



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